

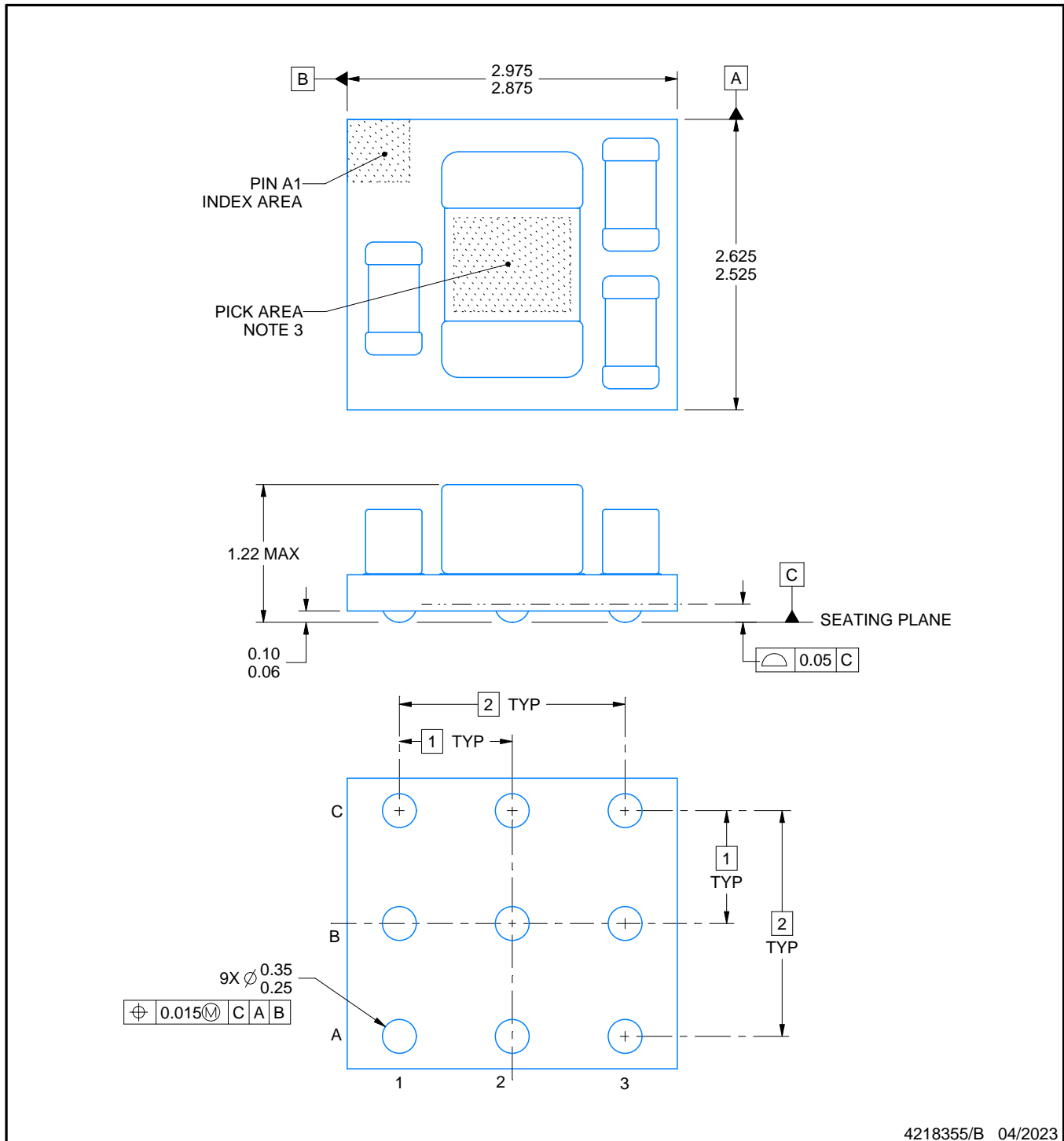


PACKAGE OUTLINE

SIP0009A

MicroSiP™ - 1.22 mm max height

MICRO SYSTEM IN PACKAGE



4218355/B 04/2023

MicroSiP is a trademark of Texas Instruments.

NOTES:

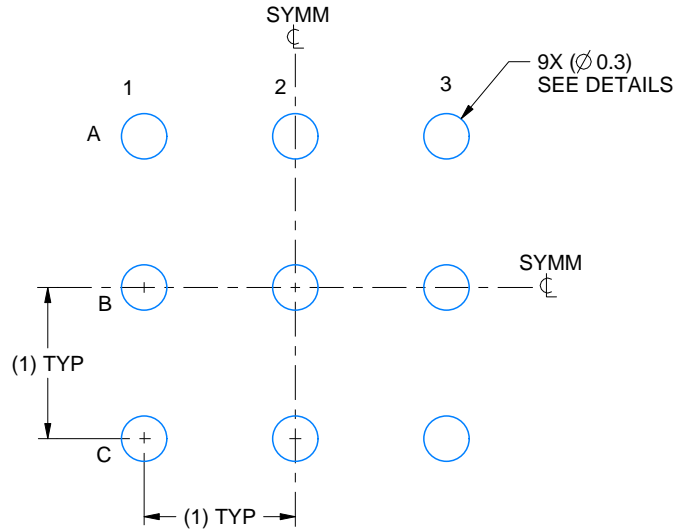
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. For pick and place nozzle recommendation, see product datasheet.
4. Location, size and quantity of each component are for reference only and may vary.

EXAMPLE BOARD LAYOUT

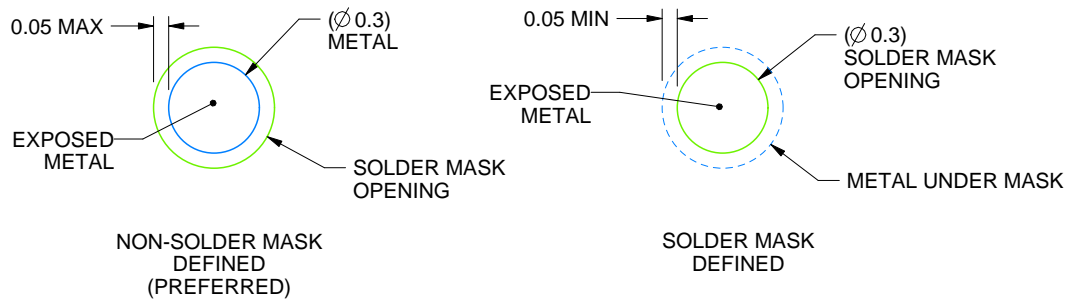
SIP0009A

MicroSiP™ - 1.22 mm max height

MICRO SYSTEM IN PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:20X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

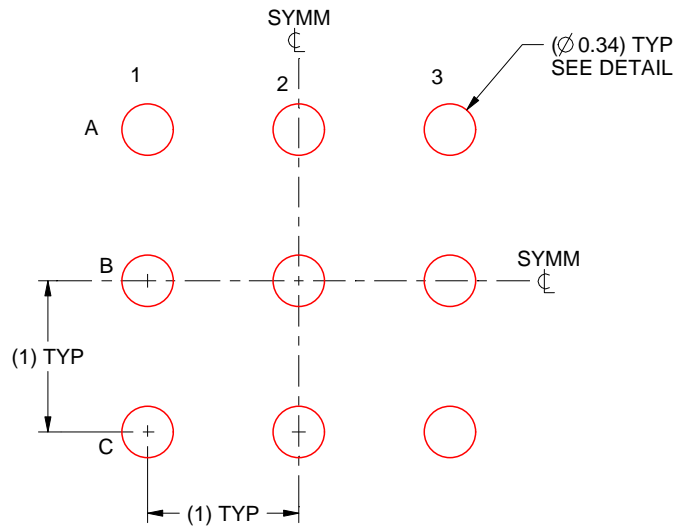
5. For more information, see Texas Instruments literature number SBVA017 (www.ti.com/lit/sbva017).

EXAMPLE STENCIL DESIGN

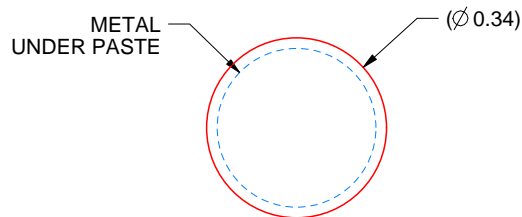
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MicroSiP™ - 1.22 mm max height

MICRO SYSTEM IN PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:20X



SOLDER PASTE DETAIL
TYPICAL

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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